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- as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))

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(54) Title: CLEANING AGENT FOR REMOVAL OF SOLDERING FLUX

(57) Abstract: A composition effective for removing solder fluxes either as a concentrated material or when diluted with water. The composition is effective in removing all types of solder fluxes including rosin type, resin type, no-clean, low residue, lead-free, organic acid and water soluble smoldering fluxes. The composition comprises tripropylene glycol butyl ether and an alkali and has a pH of greater than 7.5. The composition may contain additional optional solvents and additives to enhance cleaning of articles or to impart other properties to the composition. The composition can be contacted with a surface to be cleaned in a number of ways and under a number of conditions depending on the manufacturing or processing variables present.



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